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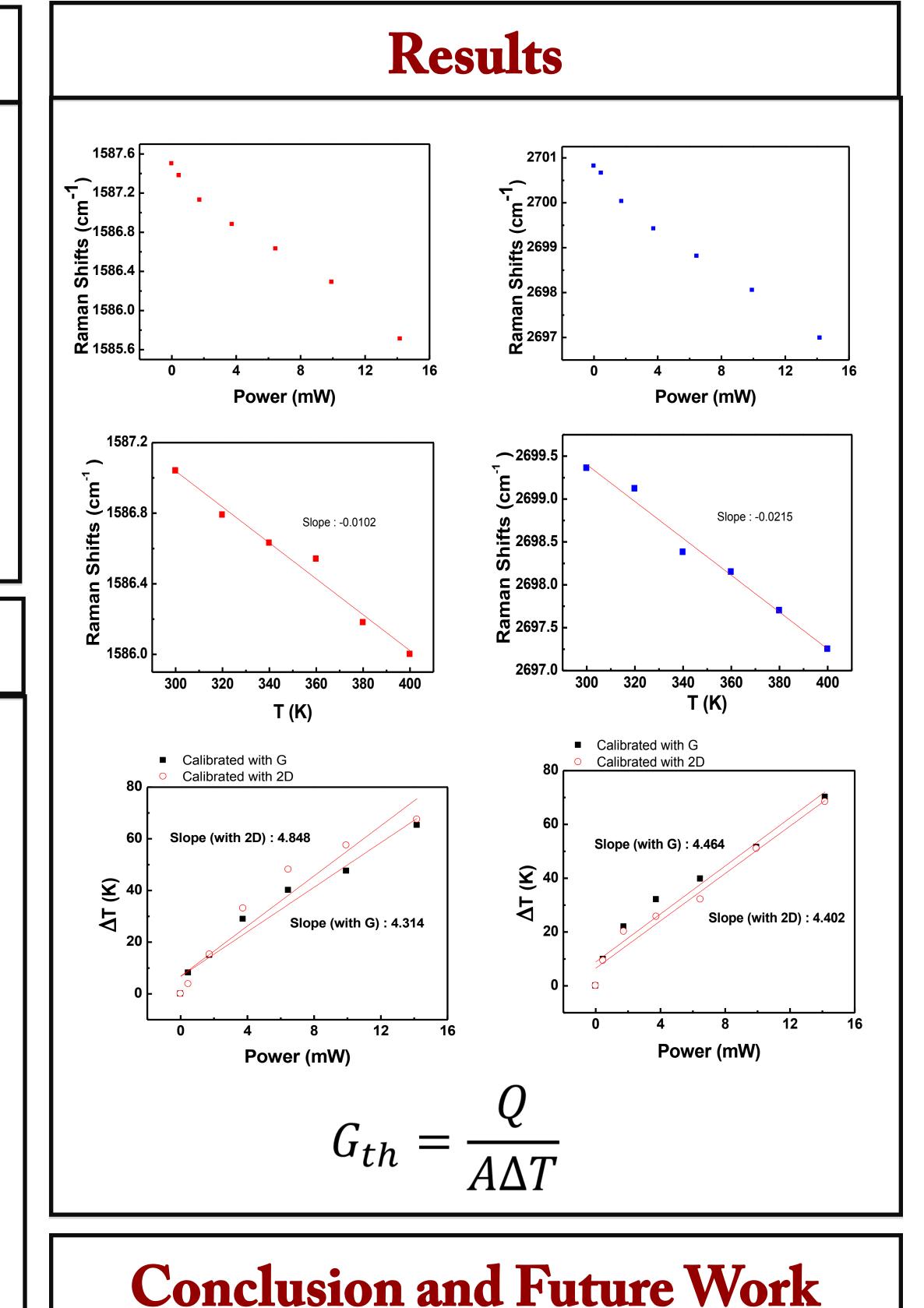
Ming Hsieh Department of Electrical Engineering

## **Optical Characterization of Thermal Transport Across Graphene/h-BN** Hetero-junction

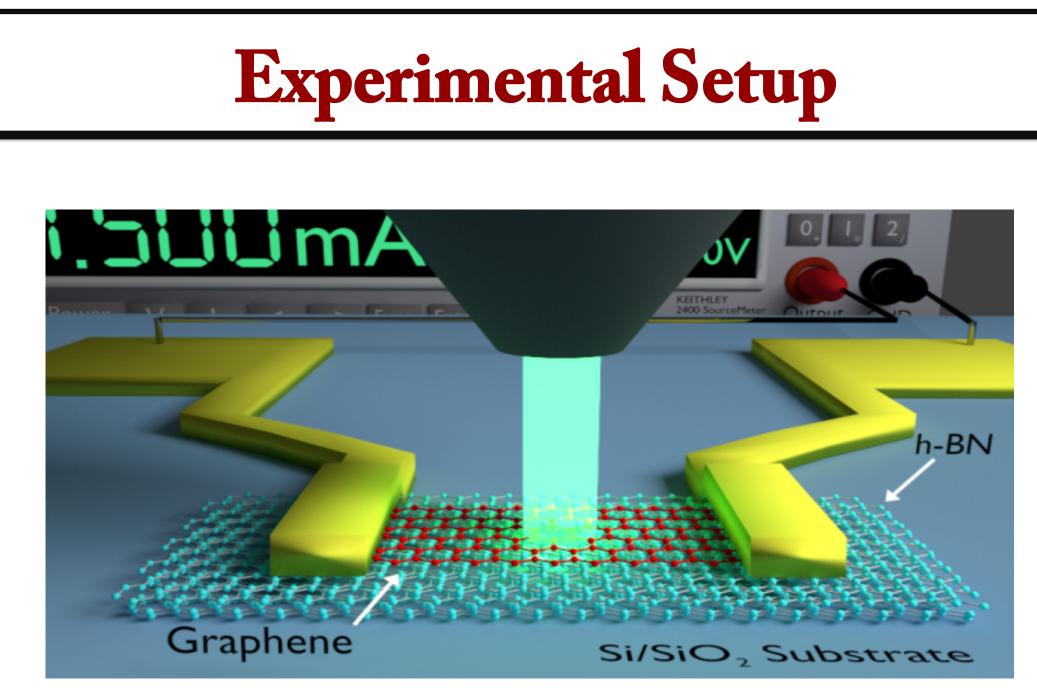
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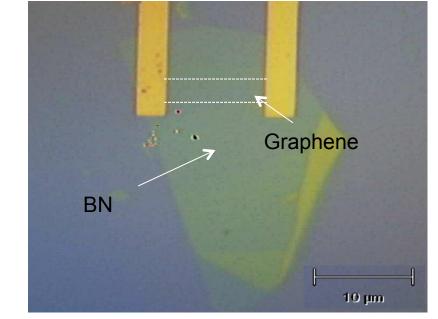
#### **Motivation & Introduction**

- Emergence of novel 2d hetero-structure devices
- Interesting transport phenomenon, rectification • and negative differential resistance in graphene based devices
- The operating temperature and device



- performance affected by interfacial thermal conductance
- Experimental Measurements of interfacial heat transport across the junctions lacking





### **Experimental Method**

- The fabricated device is placed on a cryostat
- Joule heating of underlying graphene layer using applied current ( $P=I^2R$ )
- Raman spectra of Graphene (G band (1580 cm<sup>-1</sup>), 2D band (2680 cm<sup>-1</sup>) and h-BN (1370 cm<sup>--1</sup>) downshifts with temperature
- Calibrate downshift as a function of Temperature
- Measure downshift of Raman spectra for every 0.25 mA increment of current
- Use the calibration graph to obtain the change in temperature as a function of Power applied

- $G_{th}$  is reported to be 7.41 $\pm$ 0.43 MWm<sup>-2</sup>K<sup>-1</sup>
- Interface quality needs to be improved for higher Conductance
- Currently working on measurement of thermal ullettransport across hetero-junction between graphene and various other 2d materials

#### References

Chen, Chun-Chung, Zhen Li, Li Shi, and Stephen B. Cronin, "Thermal Interface Conductance across a Graphene/hexagonal Boron Nitride Heterojunction." Appl. Phys. Lett. 104, 081908 (2014)

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